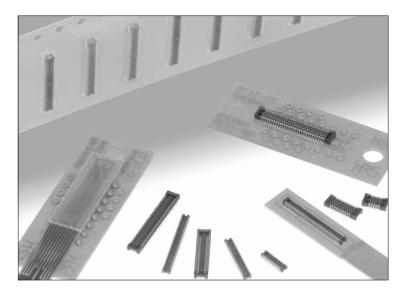
0.4 mm Pitch, 0.98 mm Mated Height, Board-to-Board / Board-to-FPC Connectors

DF37 Series



Features

1. Reduced size and board-occupied area

With the mated height of 0.98 mm, width of 2.98mm and length of 8.22 mm (30 positions) the connectors are one of the smallest in its class.

Sufficiently large flat areas allow pick-up with vacuum nozzles of automatic placement equipment.

- 2. Reliable electrical and mechanical connection Despite its small mated height, unique contact configuration, with a 2-point contacts and effective mating length of 0.25mm, assures highly reliable connection while confirming a complete mating with a definite tactile feel.
- 3. Self alignment

Recognizing the difficulties of mating extremely small connectors in limited spaces, the connectors will self-align within 0.3mm.

4. Physical shock and vibration protection

2-point contact assures electrical connection in a shock or vibration applications.

5. Solder wicking prevention

Nickel barriers (receptacles) and unique forming of the contacts (headers) prevent un-intentional solder wicking.

6. Contamination protection

Insulator walls protect the contact areas against flux splatter or other physical particles contamination.

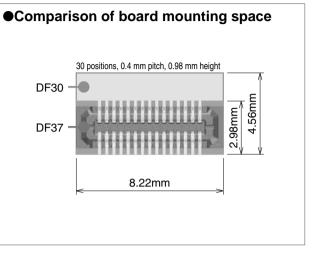
7. RoHS compliant

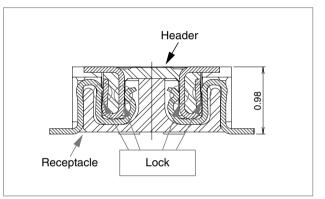
All components and materials comply with the requirements of EU Directive 2002/95/EC.

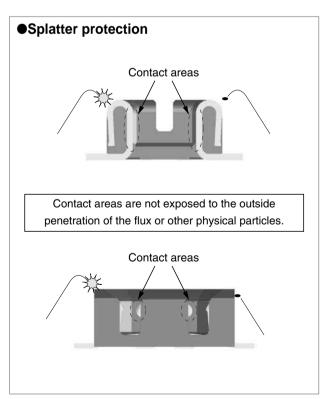
Applications

Mobile phones, digital cameras, digital camcorders and other thin portable devices requiring high reliability board-toboard/ board-to-FPC connections.

Further reduction of the board space.







The product information in this catalog is for reference only. Please request the Engineering Drawing for the most current and accurate design information. DF37 Series 0.4 mm Pitch, 0.98 mm Mated Height, Board-to-Board / Board-to-FPC Connectors

Specifications

Ratings	Current rating	0.3 A	Operating temperature range	-35°C to +85°C (Note 1)	Storage temperature range	-10°C to +60°C (Note 2)
0	Voltage rating	30 V AC, DC	Operating humidity range	RH 20% to 80%	Storage humidity range	RH 40% to 70% (Note 2)

Item	Specification	Conditions
1.Insulation resistance	50 MΩ min	100 V DC
2.Withstanding voltage	No flashover or insulation breakdown	100 V AC / 1minute
3.Contact resistance	100 mΩ max.	20 mV AC, 1 kHz, 1 mA
4.Vibration	No electrical discontinuity of 1 μ s or longer No damage or parts dislocation	Frequency: 10 to 55 Hz, single amplitude of 0.75 mm, 2 hours, 3 axis
5.Humidity	Contact resistance: 100 m Ω max., Insulation resistance: 25 M Ω min.	96 hours at 40 \pm 2°C and humidity of 90 to 95% No damage or parts dislocation
6.Temperature cycle	Contact resistance: 100 m Ω max., Insulation resistance: 50 M Ω min. No damage or parts dislocation	-55° C → 5 to 35° C → 85° C → 5 to 35° C Time: 30 min. → 10 min. → 30 min. → 10 min. 5 cycles
7.Durability	Contact resistance: 100 mΩ max.	10 cycles
8.Resistance to soldering heat	No deformation of components affecting performance	Reflow: At the recommended temperature profile Manual soldering: 350°C for 3 seconds

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" here refers to products stored for a long period prior to board mounting and use. The operating temperature and humidity range covers the non-conducting condition of connectors after board mounting and the temporary storage conditions of transportation, etc.

Materials

Receptacle

Part	Material	Finish	Remarks
Insulator	LCP	Color: Black	UL94V-0

Header

Part	Material	Finish	Remarks
Contacts	Phosphor bronze	Gold plated	

Ordering Information

Receptacles



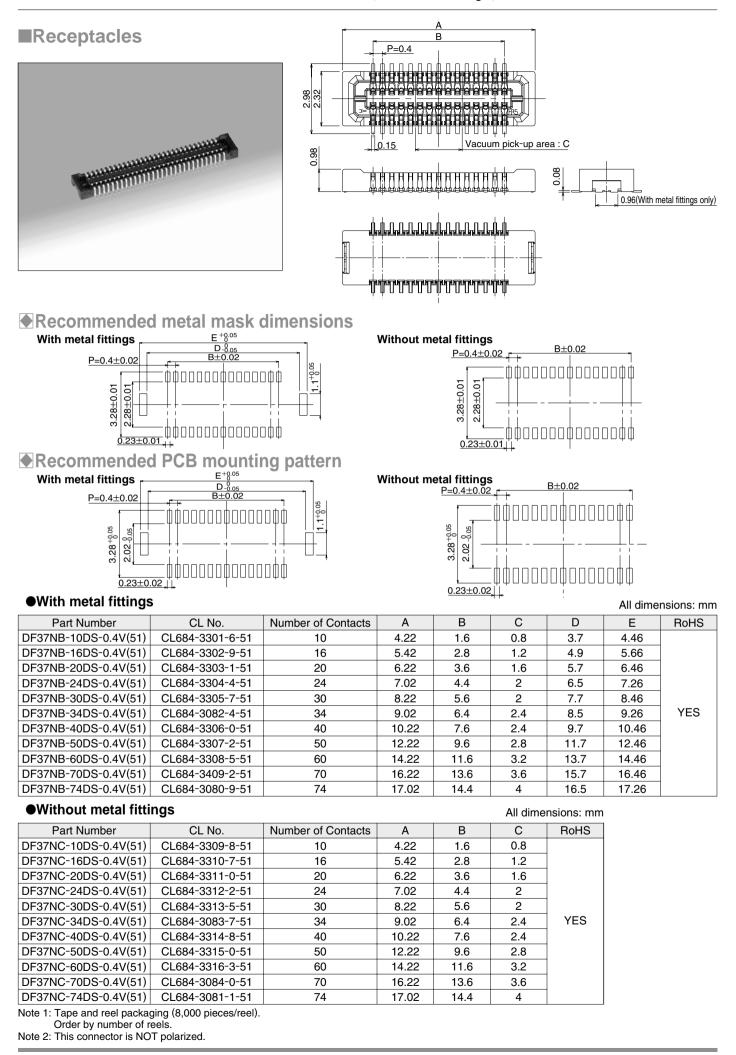
Series name : DF37N	Connector style
Onfiguration	DS: Receptacle
B: With metal fittings	Ontact pitch : 0.4 mm
C: Without metal fittings	Terminal type V: SMT vertical mount
Number of contacts	Packaging
10, 16, 20, 24, 30, 34, 40, 50, 60, 70, 74	(51): Embossed tape packaging (8,000 pieces per reel)
	(53): Embossed tape packaging (1,000 pieces per reel)

Headers

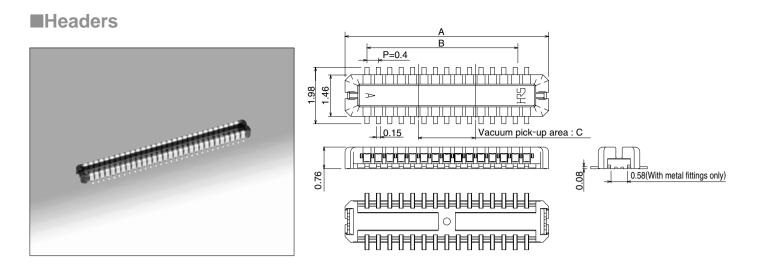
$\frac{DF 37}{10} \frac{\#}{20} - \frac{*}{60} \frac{DP}{10} - \frac{0.4}{60} \frac{V}{60} \frac{(**)}{60}$

Series name : DF37	Connector style
Configuration	DP: Header
B: With metal fittings	Ontact pitch : 0.4 mm
C: Without metal fittings	Terminal type V: SMT vertical mount
Number of contacts	Packaging
10, 16, 20, 24, 30, 34, 40, 50, 60, 70, 74	(51): Embossed tape packaging (8,000 pieces per reel)
	(53): Embossed tape packaging (1,000 pieces per reel)

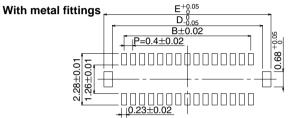
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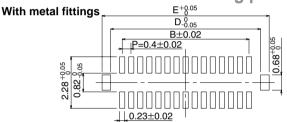
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Recommended metal mask dimensions

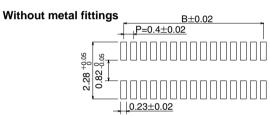


Recommended PCB mounting pattern



•With metal fittings

Without metal fittings	B <u>B±0.02</u>
	P=0.4±0.02
5 5	
<u>28+0.</u> 26±0.	
~	
-	0.23±0.02



All dimensions: mm

Part Number	CL No.	Number of Contacts	А	В	С	D	E	RoHS
DF37B-10DP-0.4V(51)	CL684-3037-0-51	10	3.14	1.6	0.8	2.62	3.38	
DF37B-16DP-0.4V(51)	CL684-3057-7-51	16	4.34	2.8	1.2	3.82	4.58	
DF37B-20DP-0.4V(51)	CL684-3008-1-51	20	5.17	3.6	1.6	4.62	5.38	
DF37B-24DP-0.4V(51)	CL684-3009-4-51	24	5.94	4.4	2	5.42	6.18	
DF37B-30DP-0.4V(51)	CL684-3010-3-51	30	7.14	5.6	2	6.62	7.38	
DF37B-34DP-0.4V(51)	CL684-3064-2-51	34	7.94	6.4	2.4	7.42	8.18	YES
DF37B-40DP-0.4V(51)	CL684-3011-6-51	40	9.14	7.6	2.4	8.62	9.38	
DF37B-50DP-0.4V(51)	CL684-3012-9-51	50	11.14	9.6	2.8	10.62	11.38	
DF37B-60DP-0.4V(51)	CL684-3013-1-51	60	13.14	11.6	3.2	12.62	13.38	
DF37B-70DP-0.4V(51)	CL684-3014-4-51	70	15.14	13.6	3.6	14.62	15.38	
DF37B-74DP-0.4V(51)	CL684-3071-8-51	74	15.94	14.4	4	15.42	16.18	

•Without metal fittings

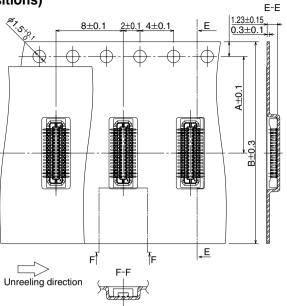
Without metal fittings All dimension						nsions: mm
Part Number	CL No.	Number of Contacts	А	В	С	RoHS
DF37C-10DP-0.4V(51)	CL684-3039-5-51	10	3.14	1.6	0.8	
DF37C-16DP-0.4V(51)	CL684-3058-0-51	16	4.34	2.8	1.2	
DF37C-20DP-0.4V(51)	CL684-3024-8-51	20	5.17	3.6	1.6	
DF37C-24DP-0.4V(51)	CL684-3025-0-51	24	5.94	4.4	2	
DF37C-30DP-0.4V(51)	CL684-3026-3-51	30	7.14	5.6	2	
DF37C-34DP-0.4V(51)	CL684-3085-2-51	34	7.94	6.4	2.4	YES
DF37C-40DP-0.4V(51)	CL684-3027-6-51	40	9.14	7.6	2.4	
DF37C-50DP-0.4V(51)	CL684-3028-9-51	50	11.14	9.6	2.8	
DF37C-60DP-0.4V(51)	CL684-3029-1-51	60	13.14	11.6	3.2	
DF37C-70DP-0.4V(51)	CL684-3030-0-51	70	15.14	13.6	3.6	
DF37C-74DP-0.4V(51)	CL684-3073-3-51	74	15.94	14.4	4	

Note 1: Tape and reel packaging (8,000 pieces/reel). Order by number of reels. Note 2: This connector is NOT polarized.

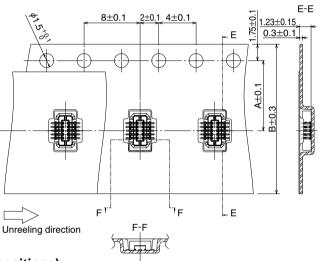
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Packaging Specifications Embossed Carrier Tape Dimensions

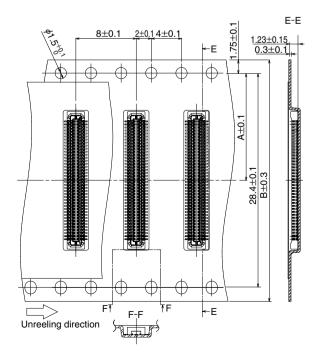
•Receptacle (20 and above positions)



•Receptacle (less than 20 positions)

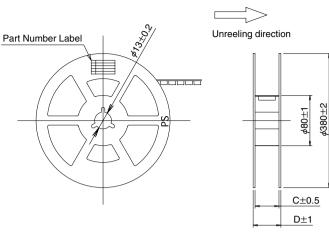


•Receptacle (more than 60 positions)



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•Reel Dimensions



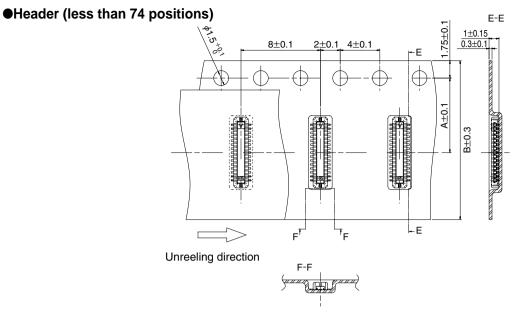
All dimensions: mm

Part Number	А	В	С	D
DF37N#-10DS-0.4V(51)	7.5	16	17.5	21.5
DF37N#-16DS-0.4V(51)	7.5	16	17.5	21.5
DF37N#-20DS-0.4V(51)	7.5	16	17.5	21.5
DF37N#-24DS-0.4V(51)	7.5	16	17.5	21.5
DF37N#-30DS-0.4V(51)	11.5	24	25.5	29.5
DF37N#-34DS-0.4V(51)	11.5	24	25.5	29.5
DF37N#-40DS-0.4V(51)	11.5	24	25.5	29.5
DF37N#-50DS-0.4V(51)	11.5	24	25.5	29.5
DF37N#-60DS-0.4V(51)	11.5	24	25.5	29.5
DF37N#-70DS-0.4V(51)	14.2	32	33.5	37.5
DF37N#-74DS-0.4V(51)	14.2	32	33.5	37.5

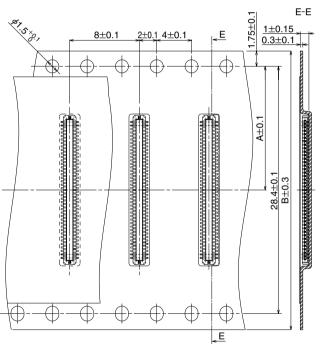
#: B or C

Tape and reel packaging (8,000 pieces/reel).

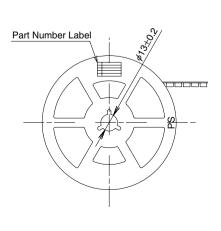
Embossed Carrier Tape Dimensions

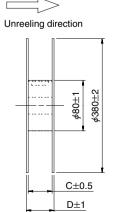


•Header (74 positions and above)



Reel Dimensions





	В	С	D
5.5	12	13.5	17.5
7.5	16	17.5	21.5
7.5	16	17.5	21.5
7.5	16	17.5	21.5
11.5	24	25.5	29.5
11.5	24	25.5	29.5
11.5	24	25.5	29.5
11.5	24	25.5	29.5
11.5	24	25.5	29.5
11.5	24	25.5	29.5
14.2	32	33.5	37.5
	7.5 7.5 7.5 11.5 11.5 11.5 11.5 11.5 11.	7.5 16 7.5 16 7.5 16 7.5 16 11.5 24 11.5 24 11.5 24 11.5 24 11.5 24 11.5 24 11.5 24 11.5 24 11.5 24 11.5 24	7.5 16 17.5 7.5 16 17.5 7.5 16 17.5 11.5 24 25.5 11.5 24 25.5 11.5 24 25.5 11.5 24 25.5 11.5 24 25.5 11.5 24 25.5 11.5 24 25.5 11.5 24 25.5 11.5 24 25.5 11.5 24 25.5 11.5 24 25.5 11.5 24 25.5

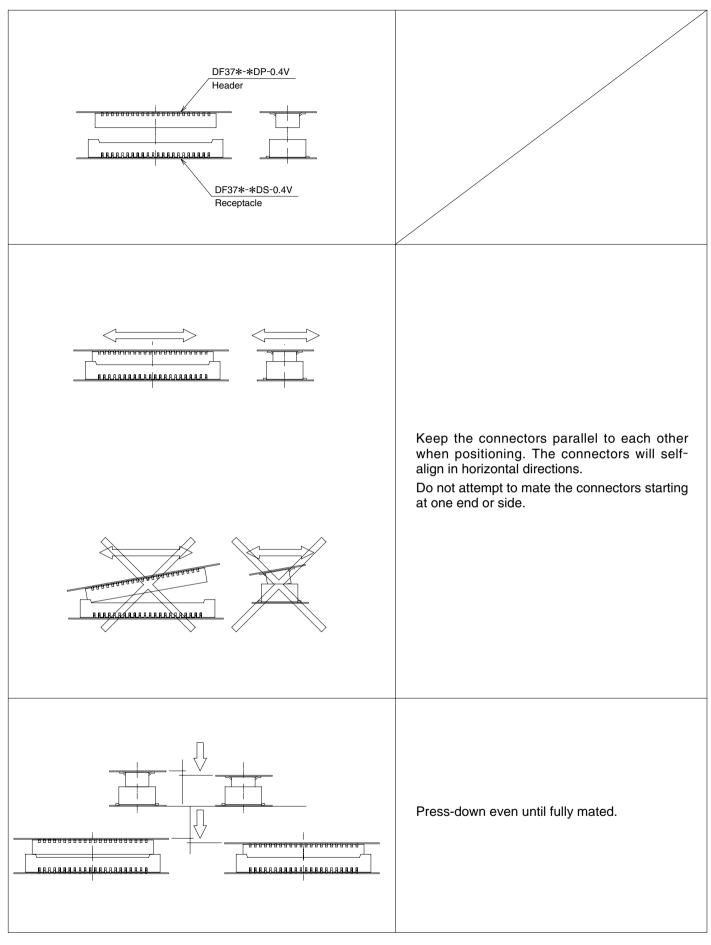
Tape and reel packaging (8,000 pieces/reel).

All dimensions: mm

Usage Recommendation	າຣ
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1.Recommended temperature profile	
	Temperature (°C)
	250 ⁻
	220°C
	200 - 60sec max
	180°C
	150 - 150°C - 7
	100 90~120sec
	50
	50 -/ Room temperature
	0 50 100 150 200 250 300
	Time (sec.)
	Note 1: Up to 2 cycles of Reflow soldering are possible under the same conditions, provided that there is a return to normal temperature between the first and second cycle.
	Note 2: The temperature profile indicates the board surface
	temperature at the point of contacts with the connector
	terminals.
2.Recommended manual soldering	Manual soldering: 340±10°C for 3 seconds
3.Recommended screen thickness and open	
area ratio (Pattern area ratio)	Thickness: 0.12 mm
aiea ialio (i alleiii aiea ialio)	Open area ratio: Receptacle:80%, Plug: 70%
4.Board warpage	
	Open area ratio: Receptacle:80%, Plug: 70%
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4.Board warpage 5.Cleaning conditions	Open area ratio: Receptacle:80%, Plug: 70% Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points. Cleaning is not recommended. When cleaning, please evaluate as it can deteriorate the performance including mechanical operation and environmental resistance.
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4.Board warpage 5.Cleaning conditions	 Open area ratio: Receptacle:80%, Plug: 70% Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points. Cleaning is not recommended. When cleaning, please evaluate as it can deteriorate the performance including mechanical operation and environmental resistance. Mating and un-mating of the connectors when not soldered on the boards is not recommended as this may cause deformation of the terminals, damage to the contacts or insulators. Mated connectors should not carry weight of the board by themselves. Provide some other support of the boards. When mating/un-mating do not twist or lift by the corners. Apply the forces evenly across the entire length and width of the connectors taking care NOT to damage or deform soldered terminations. Exercise extreme caution when mating/ un-mating when the connector is mounted on a nonrigid (flexible) substrate.

Handling Precautions when Mating Connectors



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Handling Precautions When Un-mating Connectors

